

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
400)/	160mΩ @ V _{GS} = 10V	2.6A
100V	200mΩ @ V _{GS} = 4.5V	2.3A

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Power Management Functions
- Battery Operated Systems and Solid-State Relays
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.

Features and Benefits

- Low Gate Threshold Voltage
- Low Input Capacitance
- · Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

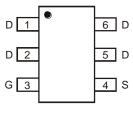
Mechanical Data

- Case: TSOT26
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.015 grams (Approximate)

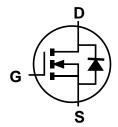




Top View



Top View Pin-Out



Equivalent Circuit

Ordering Information (Note 4)

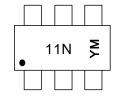
Part Number	Case	Packaging
DMN10H170SVT-7	TSOT26	3,000/Tape & Reel
DMN10H170SVT-13	TSOT26	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

TSOT26



11N = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2014		2015	2016		2017	2018		2019	2020	1	2021
Code	В		С	D		Е	F		G	Н		I
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V _{DSS}	100	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 6) $V_{GS} = 10V$ Steady $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$			I _D	2.6 2.1	А
Pulsed Drain Current (10µs pulse, duty cycle ≦1%)	I _{DM}	11.2	Α		
Maximum Body Diode Continuous Current (Note 6)	Is	2.0	А		

Thermal Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic		Symbol	Value	Units	
Total Dawer Dissination	(Note 5)	Б	1.2	W	
Total Power Dissipation	(Note 6)	P _D	1.7		
Thermal Resistance, Junction to Ambient	(Note 5)	-	101		
memal Resistance, Junction to Ambient	(Note 6)	$R_{\theta JA}$	73	°C/W	
Thermal Resistance, Junction to Case	(Note 6)	$R_{ heta JC}$	15		
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

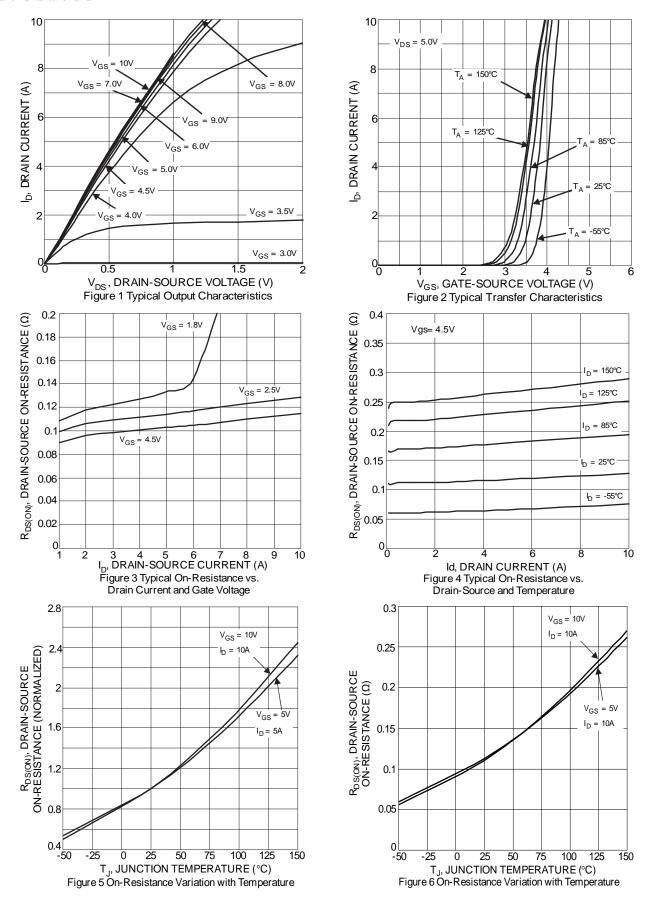
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)			•				
Drain-Source Breakdown Voltage	BV _{DSS}	100	_	_	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1.0	μΑ	$V_{DS} = 100V, V_{GS} = 0V$	
Gate-Body Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	1.0	2.0	3.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance		_	115	160	mΩ	$V_{GS} = 10V, I_D = 5.0A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	_	124	200	11122	$V_{GS} = 4.5V, I_D = 5.0A$	
Diode Forward Voltage	V _{SD}	_	0.9	1.0	V	V _{GS} = 0V, I _S = 10A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}		1,167	_		V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	36	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	25	_			
Gate Resistance	Rg	_	1.3	_	Ω	VDS = 0V, VGS = 0V, f = 1.0MHz	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	4.9	_			
Total Gate Charge (V _{GS} = 10V)	Qg	_	9.7		C	V 00V I 40 0A	
Gate-Source Charge	Q _{gs}	_	2.0	_	nC	$V_{DS} = 80V, I_{D} = 12.8A$	
Gate-Drain Charge	Q_{gd}	_	2.0	_			
Turn-On Delay Time	t _{D(on)}	_	10	_			
Turn-On Rise Time	t _r	_	11	_		$V_{DD} = 50V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(off)}	_	42	_	nS	$R_G = 25\Omega$, $I_D = 12.8A$	
Turn-Off Fall Time	t _f	_	12	_			
Reverse Recovery Time	t _{rr}	_	30	_	nS	Vac - 0V Ia-12 9A di/dt-1004/va	
Reverse Recovery Charge	Qrr	_	35	_	$rac{NS}{nC}$ V _{GS} = 0V, I _S =12.8A, di/dt=100/		

Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

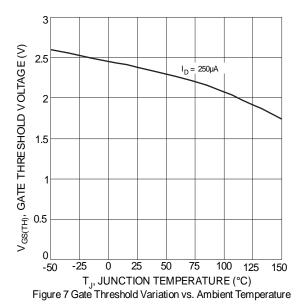
^{7.} Short duration pulse test used to minimize self-heating effect.

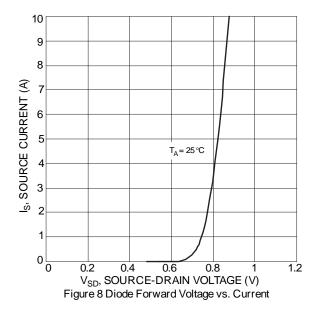
^{8.} Guaranteed by design. Not subject to product testing.

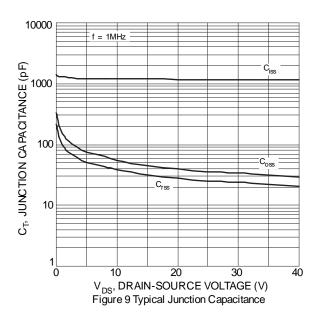


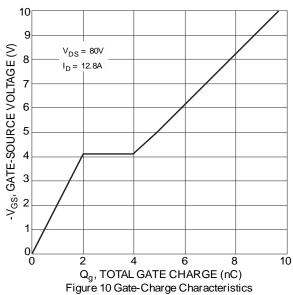


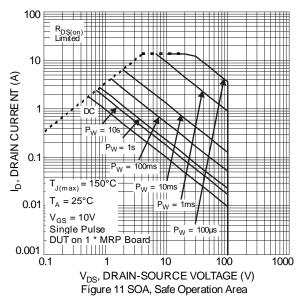




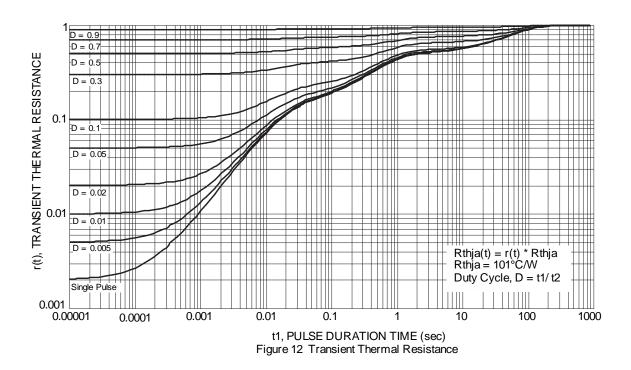






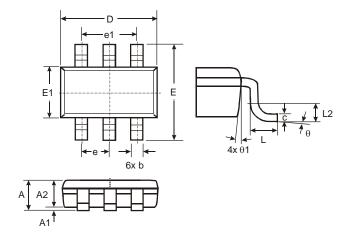






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

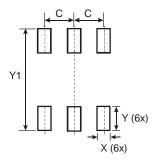


	TSOT26								
Dim	Min	Max	Тур						
Α	_	1.00	_						
A1	0.01	0.10	-						
A2	0.84	0.90	_						
D	_	_	2.90						
Ε	_	_	2.80						
E1	_	_	1.60						
b	0.30	0.45	_						
С	0.12	0.20	-						
е	-	_	0.95						
e1	_	_	1.90						
L	0.30	0.50							
L2	-	_	0.25						
θ	0°	8°	4°						
θ1	4°	12°	-						
All Dimensions in mm									



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.950
Х	0.700
Υ	1.000
Y1	3.199

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